

MEDIA RELEASE

SINGAPORE'S UTAC TO CO-DEVELOP 2.5D THROUGH-SILICON-INTERPOSER WITH A*STAR'S INSTITUTE OF MICROELECTRONICS FOR VOLUME MANUFACTURING

1. Singapore, 28 March, 2013 - A*STAR's Institute of Microelectronics (IME) and United Test and Assembly Center (UTAC), a leading outsourced assembly and test (OSAT) provider, have announced a collaboration to develop a 2.5D Through-Silicon-Interposer (TSI) platform which will enable UTAC to join the scarce list of suppliers in offering fine-pitch 2.5D TSI packaging solutions.

2. This collaboration builds on the technology expertise of both partners and leverages IME's cutting-edge 300mm Through-Silicon-Via (TSV)/TSI fabrication and assembly infrastructure to develop and prototype 2.5D TSI-based systems. IME will contribute its deep R&D experience in design and advanced packaging to develop optimized solutions to address electrical, thermal, thermo-mechanical and reliability requirements for applications including mobile devices such as tablets and smart phones. The optimized 2.5D TSI technology from this collaboration will be transferred to UTAC for high volume manufacturing, enabling UTAC to shorten their time-to-market significantly.

3. With the 2.5D/3D IC process technologies gradually being accepted by industry, IME has been actively engaging leading companies from the supply chain to drive the mass production of 2.5D/3D ICs.

4. "IME's strong commitment in accelerating industry adoption of 2.5D and 3DIC design and manufacturing as well as our breadth of expertise in 200mm and 300mm back-end-of-line (BEOL) capabilities present an attractive value proposition to companies to

collaborate with us,” said Prof. Dim-Lee Kwong, Executive Director of IME. “IME looks forward to working with our partners to develop innovative 3D IC solutions and carry 3D integration forward toward numerous applications that can be commercialized.”

5. “Leveraging on IME’s leading 3D IC capabilities, we believe that we will be able to better respond to market demands and support our customers with services that offer them faster time-to-market, strengthening our leadership in the 3D IC arena,” said Dr William John Nelson, Group President and Chief Executive Officer of UTAC.

About Institute of Microelectronics (IME)

The Institute of Microelectronics (IME) is a research institute of the Science and Engineering Research Council of the Agency for Science, Technology and Research (A*STAR). Positioned to bridge the R&D between academia and industry, IME's mission is to add value to Singapore's semiconductor industry by developing strategic competencies, innovative technologies and intellectual property; enabling enterprises to be technologically competitive; and cultivating a technology talent pool to inject new knowledge to the industry. Its key research areas are in integrated circuits design, advanced packaging, bioelectronics and medical devices, micro-electro-mechanical systems, nanoelectronics, and photonics. For more information about IME, please visit <http://www.ime.a-star.edu.sg>.

About Agency for Science, Technology and Research (A*STAR)

The Agency for Science, Technology and Research (A*STAR) is Singapore's lead public sector agency that fosters world-class scientific research and talent to drive economic growth and transform Singapore into a vibrant knowledge-based and innovation driven economy. A*STAR oversees 20 biomedical sciences and physical sciences and engineering research entities, located in Biopolis and Fusionopolis as well as their vicinity. These two R&D hubs house a bustling and diverse community of local and international research scientists and engineers from A*STAR's research entities as well as a growing number of corporate laboratories. Please visit www.a-star.edu.sg

About UTAC Group

UTAC Group (“UTAC Holdings and subsidiaries”) is a leading independent provider of semiconductor assembly and testing services for a broad range of integrated circuits including mixed-signal, analog and memory. The Group offers a full range of package and test development, engineering and manufacturing services and solutions to a worldwide customer base, comprising leading integrated device manufacturers (IDMs), fabless companies and wafer foundries. UTAC Group operates manufacturing facilities in Singapore, Thailand, Taiwan and China in addition to its global sales network.

Media Contact:

For IME:

Cindy Chew

Institute of Microelectronics

DID: +65 6770 5375

Email: chewwfc@ime.a-star.edu.sg

For UTAC

Name: Josephine Lim

Tel: +65 6481 0033

Email: Josephine_lim@utacgroup.com